



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TO-262/263 (D²PAK)

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
85/85	292	185,504	85°C, 85%RH	0	0.00
BOND INT	2,040	1,020,000	200°C + N2	0	0.00
HAST	5,557	560,000	130°C, 85%RH	0	0.00
Power Cycle	3,700	31,519,456	DELTA Tj=100	0	0.00
Pressure Pot	12,614	1,210,444	121°, 15 PSIG	0	0.00
Solder DUNK	1,760	5,280	260°C, 10SEC	0	0.00
Solderability	1,395	12,600	883 M2003	0	0.00
Temp Cycle	15,793	9,244,236	-65°C-150°C	0	0.00
Thermal Shock	3,600	360,000	-60°C-150°C	0	0.00